

L Number	Hits	Search Text	DB	Time stamp
1	44	power adj laminate	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:13
2	22	interposer with (power adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:17
3	19	("4489364"   "4811082"   "4840924"   "4862243"   "4984054"   "5011067"   "5049969"   "5107586"   "5220490"   "5260597"   "5294754"   "5331195"   "5414637"   "5465004"   "5473196"   "5475236"   "5502333"   "5529950"   "5786628").PN.	USPAT	2004/03/15 10:16
4	2643	(power adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
5	26201	(ground adj (layer or plane))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
6	1085	(( power adj (layer or plane))) and (( ground adj (layer or plane)))	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
7	928	(( (power adj (layer or plane))) and ((ground adj (layer or plane)))) and (chip or IC or die or component)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:18
8	873	(((( power adj (layer or plane))) and (( ground adj (layer or plane)))) and (chip or IC or die or component)) and (board or substrate)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:28
9	539	(((( (power adj (layer or plane))) and (( ground adj (layer or plane)))) and (chip or IC or die or component)) and (board or substrate)) and @pd<20010316	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/15 10:28